Laser Assisted Particle Removal

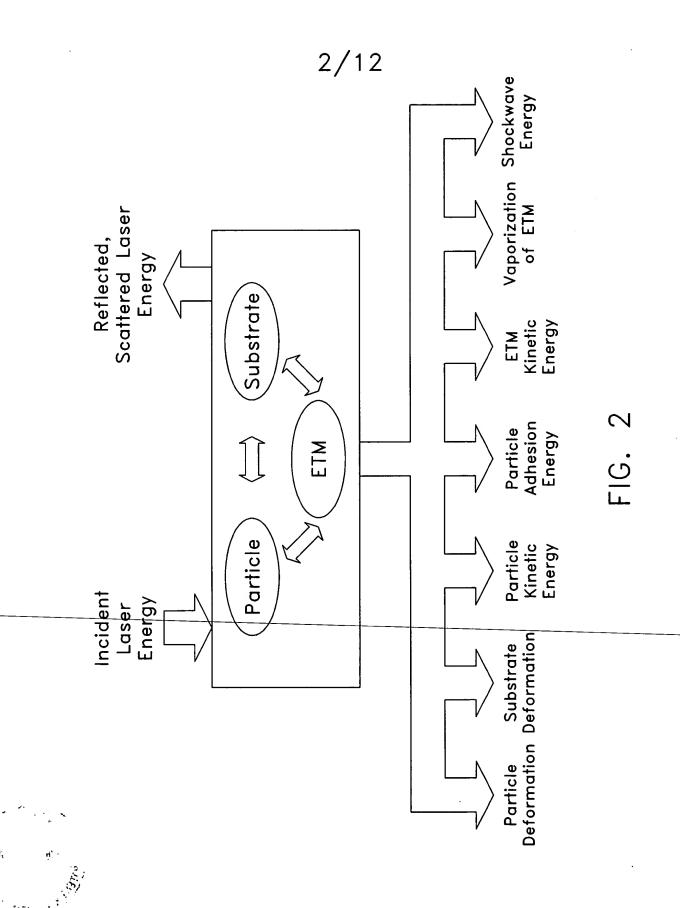
## Chemical Mechanisms

- Photochemical reactive removal
- Photo— + thermo chemical reactive removal

## Mechanical Mechanisms

- Particle deformation
- Substrate deformation
- Energy transfer medium explosive evaporation

FIG. 1



	Substrate without ETM	Rapid thermal expansion of the substrate	λ>>Particle Diameter or λ <particle diameter<br="">if α<sub>particle</sub> is Ιοw</particle>	High α <sub>substrate</sub>	Melting/Ablation of particle or substrate	Φ <sub>th</sub> =0.02-0.3 J/cm <sup>2</sup> . I <sub>th</sub> =1-30 MW/cm <sup>2</sup> t=7-30 ns
	Substrate with ETM	Microbubble formation at liquid/solid interface	λ>Particle Diameter	High α <sub>substrate</sub>	-Melting/Ablation of particle or substrate -Shockwave in ETM	Φ <sub>th</sub> =0.02-0.3 J/cm <sup>2</sup> I <sub>th</sub> =2-600 MW/cm <sup>2</sup> t=0.03-20 ns
	ЕТМ	Explosive evaporation of ETM	λ>>Particle Diameter	High α <sub>ETM</sub>	Shockwave, substrate absorption	Φ <sub>th</sub> =0.65-2.2 J/cm <sup>2</sup> I <sub>th</sub> =3-11 MW/cm <sup>2</sup>
	0	rmal of	iameter	^	lation le	3 J/cm² /cm²
	Particle	Rapid thermal expansion of particle	λ< <particle diameter<="" td=""><td>a particle of Substrate</td><td>-Melting/Ablation of particle</td><td>Φ<sub>th</sub> =0.01-0.08 J/cm<sup>2</sup> I<sub>th</sub> =1-11 MW/cm<sup>2</sup> D=20μm</td></particle>	a particle of Substrate	-Melting/Ablation of particle	Φ <sub>th</sub> =0.01-0.08 J/cm <sup>2</sup> I <sub>th</sub> =1-11 MW/cm <sup>2</sup> D=20μm
	Absorption Medium	Removal Mechanism	wavelength	Energy Absorption	Substrate Damage	Particle Removal Threshold

FIG. 5

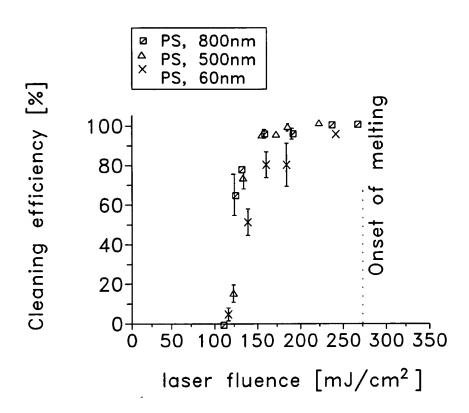


FIG. 4

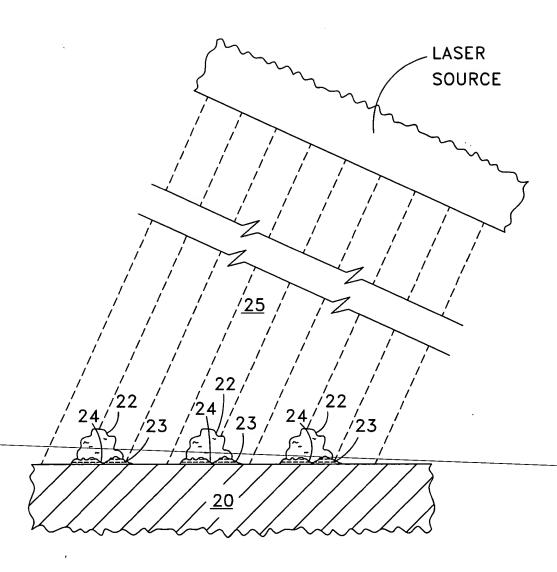


FIG. 5

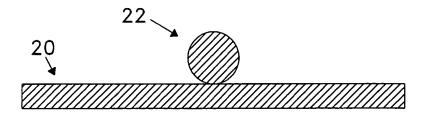


FIG. 6A

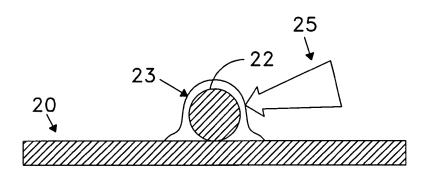


FIG. 6B

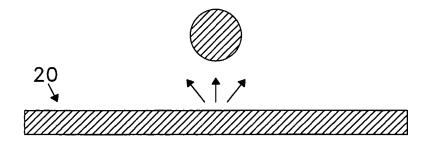


FIG. 6C

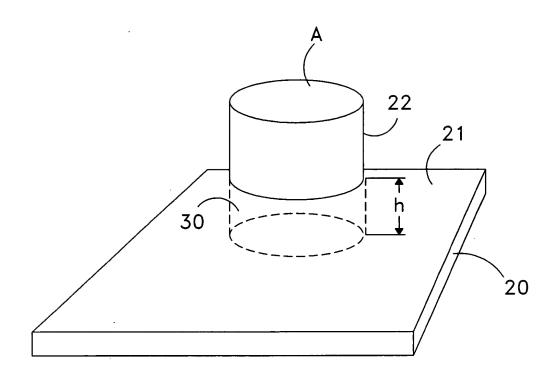
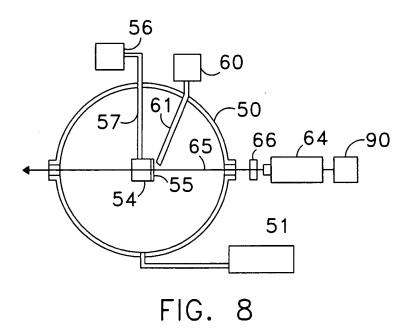


FIG. 7



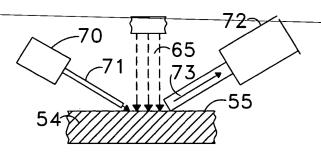


FIG. 9

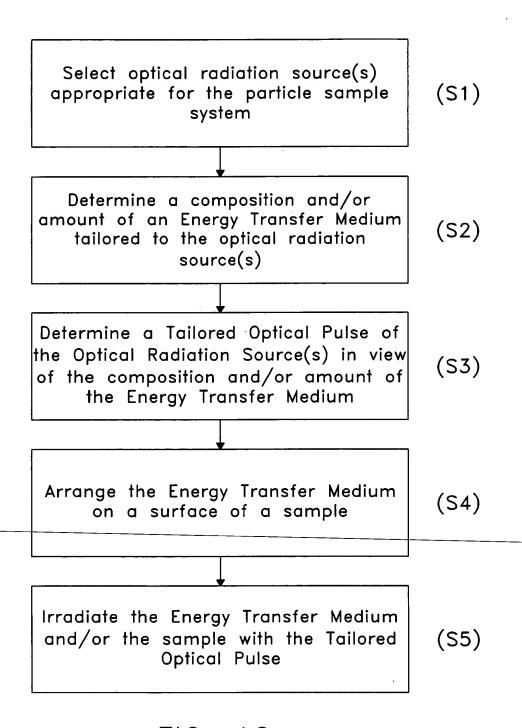


FIG. 10

<u>100</u>

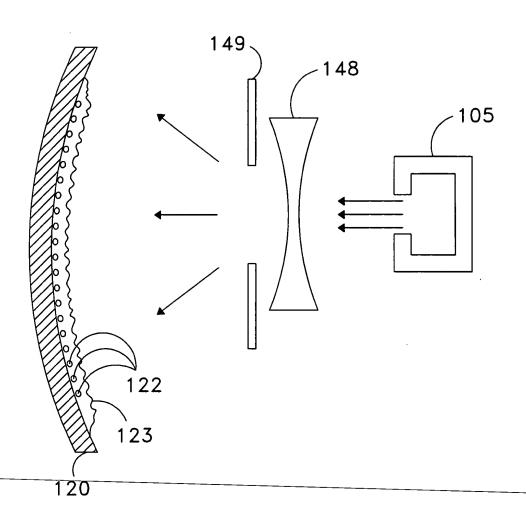


FIG. 11

<u>100</u>

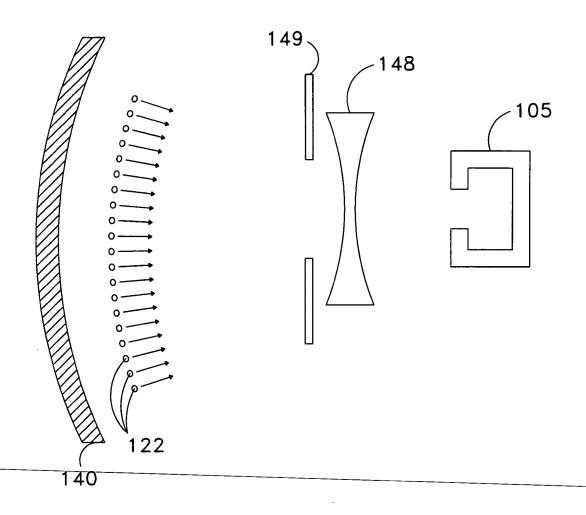


FIG. 12

<u>200</u>

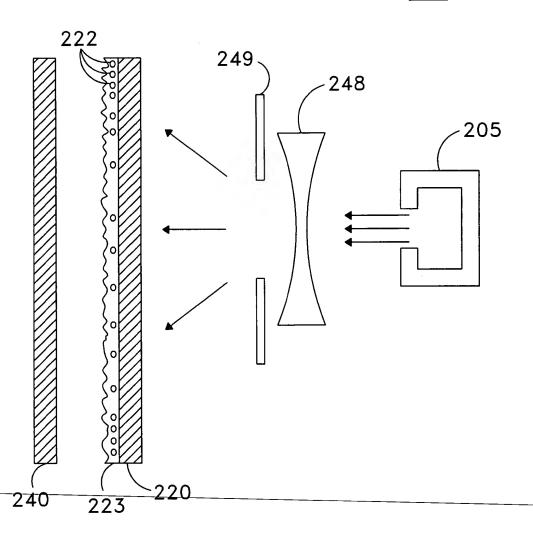


FIG. 13